

[Name of Document]	PETITION OF PATENT
[Reference number]	P130082
[To]	Mr. Kozo Oikawa Director-General, Patent Office
[IPC]	C08G 59/04
[Inventor]	
[Domicile or Residence]	c/o Laboratory, Tohto Kasei Co., Ltd., 17-14, Higashikasai 3-chome, Edogawa-ku, Tokyo
[Name]	Shuya SHINOHARA
[Inventor]	
[Domicile or Residence]	c/o Laboratory, Tohto Kasei Co., Ltd., 17-14, Higashikasai 3-chome, Edogawa-ku, Tokyo
[Name]	Masayoshi HANABUSA
[Inventor]	
[Domicile or Residence]	c/o Laboratory, Tohto Kasei Co., Ltd., 17-14, Higashikasai 3-chome, Edogawa-ku, Tokyo
[Name]	Nobuhisa SAITO
[Inventor]	
[Domicile or Residence]	c/o Laboratory, Tohto Kasei Co., Ltd., 17-14, Higashikasai 3-chome, Edogawa-ku, Tokyo
[Name]	Hiroshi NAKANISHI
[Applicant]	
[Applicant code]	000221557
[Name or Trade Name]	Tohto Kasei Co., Ltd.
[Agent]	
[Agent code]	100089406
[Attorney]	
[Name or Trade Name]	Hiroshi TANAKA
[Selected Agent]	
[Agent code]	100096563
[Attorney]	
[Name or Trade Name]	Eishiro HIGUCHI

[Selected Agent]	
[Agent code]	100110168
[Attorney]	
[Name or Trade Name]	Harumi MIYAMOTO
[Indication of Fees]	
[List number of Prepaid]	024040
[Amount Paid]	¥21,000
[List of Documents Filed]	
[Name] Specification	1
[Name] Drawing	1
[Name] Abstract	1
[Proof]	yes

【Name of Document】 Specification

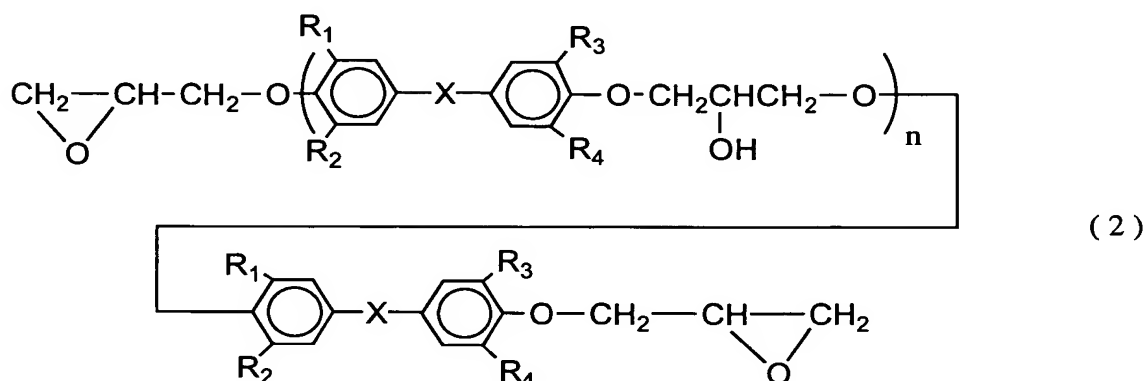
**【Title of the Invention】 EPOXY RESIN, EPOXY RESIN COMPOSITION
CONTAINING THE EPOXY RESIN AND CURED PRODUCT THEREOF**

【Claims】

【Claim 1】

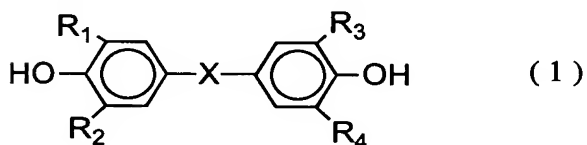
An epoxy resin represented by general formula (2),

【C 2】



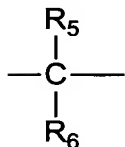
R₁-R₄ indicate hydrocarbon group of carbon number 1-6, n is 0 or integer of 1 or more and X in aromatic compound (1)

【C 2】



is not existing or following general formula

【C 3】



wherein R₁-R₆ indicates hydrogen atom or hydrocarbon group of carbon number 1-6,

obtained by reacting aromatic compound represented by general formula (1) and epihalohydrine,

having molecular weight distribution comprising, content of $n=0$

component in the epoxy resin represented by general formula (2) is 60% or less and epoxy equivalent is bigger than 250g/eq.

【Claim 2】

The epoxy resin of claim 1, wherein aromatic compound represented by general formula (1) according to claim 1, is 3,3',5,5'-tetramethyl-4,4'-dihydroxyldiphenyl methane.

【Claim 3】

An epoxy resin composition comprising the epoxy resin in accordance with any one of claims 1 or 2 and a curing agent.

【Claim 4】

The cured product of epoxy resin prepared by curing the epoxy resin composition of claim 3.

【Claim 5】

The coated product prepared by coating the epoxy resin composition on the surface of the object and by curing.

【Detailed description of the Invention】

【0001】

【Field of the Invention】

The present invention relates to the epoxy resin which is excellent at solvent dissolution stability in the viscous liquid state, semi solid state or solid state, characterized not to generate crystallinity at the normal temperature, the epoxy resin composition containing said epoxy resin and the cured product obtained by curing said epoxy resin composition.

【0002】

【Description of the Prior Art】

In the case of semi-conductor sealing material, which belongs to the electric/electronic field, improvement to high tenacity and low water absorption by high filling of silica for the purpose to protect from the problem of packaging crack was required, and various low viscous crystalline epoxy resin have been proposed (Japanese Patent Laid Open Publications 7-126574 and 2-12225 and Japanese Patent Application 9-310494).

【0003】

In the meanwhile, in the coating field, following powder coating which does not contain solvent is required from the view point of the air pollution or the working environment. Namely, a powder coating which is gentle to